

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L39	78976	(barrier liner seed) with (trench hole via damascene opening groove)	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/07/13 17:30
L40	13594	39 and (barrier liner seed) with (remove removing removal)	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/07/13 17:25
L41	5145	40 and (bottom) with (trench hole via damascene opening groove)	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/07/13 17:23
L42	1679	41 and (bottom) with (remove removing removal)	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/07/13 17:24
L43	1410	41 and (bottom) near5 (remove removing removal etch\$3)	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/07/13 17:25
L44	1173	43 and (barrier liner seed) near5(remove removing removal etch\$3)	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/07/13 17:26
L45	993	44 and (barrier liner seed) near5(form\$3 deposit\$3)	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/07/13 17:27
L46	1094	44 and (barrier liner seed) near5(form\$3 deposit\$3)	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/07/13 17:27
L47	666	46 and (barrier liner seed) near5(bottom)	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/07/13 17:28
L48	3364	interconnect\$3 with ((barrier liner lining seed) with (trench hole via damascene opening groove))	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/07/13 17:32

L49	1592	48 and ((barrier liner lining seed) with diffus\$4)	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/07/13 17:33
L50	858	49 and (bottom near5 (trench hole via damascene opening groove))	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/07/13 17:32
L51	489	50 and ((barrier liner lining seed) near5 bottom)	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/07/13 17:33
L52	362	51 and ((barrier liner lining seed) near5 (removing removal etch\$4 remov\$3))	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/07/13 17:34
L53	211	52 and ((bottom) near5 (removing removal etch\$4 remov\$3))	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/07/13 17:35